

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0				

NOTES:

1. MATERIAL

CONTACTS: COPPER ALLOY (T=0.20mm)
SHELL: SPCC OR COPPER ALLOY (T=0.30mm)
HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.

2. ELECTRICAL PERFORMANCE,

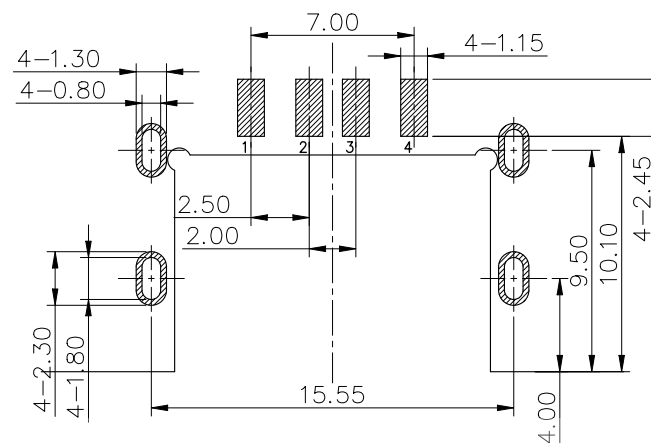
CONTACT RESISTANCE: 30MΩ MAX
CONTACT CURRENT RATING: 1.5 AMPERES
DIELECTRIC WITHSTAND VOLTAGE, 500V R.M.S
INSULATION RESISTANCE: 100MΩ MIN
OPERATING TEMPERATURE: -40° C~+85° C.

3. MECHANICAL PERFORMANCE,

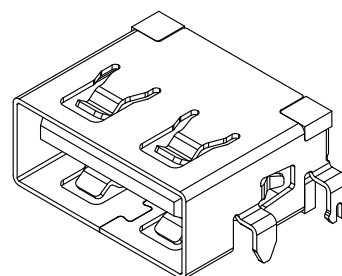
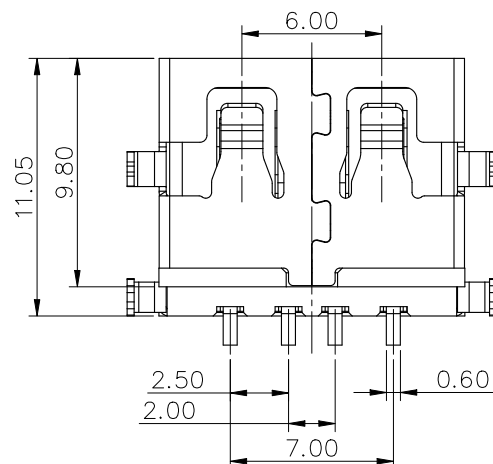
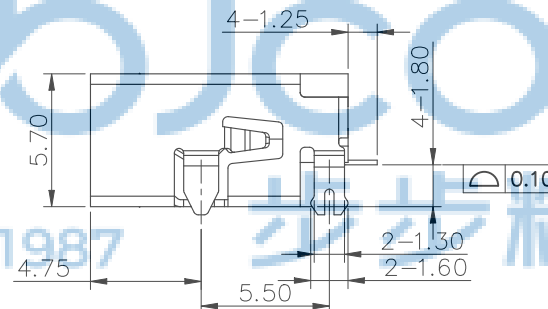
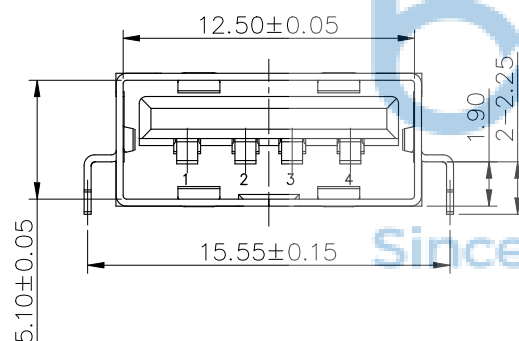
INSERTION FORCE: 3.5kgf Max
REMOVAL FORCE: 1.02kgf Min
DURABILITY: 1000 CYCLES.

4. PLATING SPECIFICATION:

CONTACTS: GOLD PLATED ON CONTACT AREA, Sn ON SOLDER AREA,
NICKEL UNDERPLATED.
SHELL: BRIGHT NICKEL PLATING OVER ALL,
NICKEL MUST BE SOLDABILITY.
HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0 .



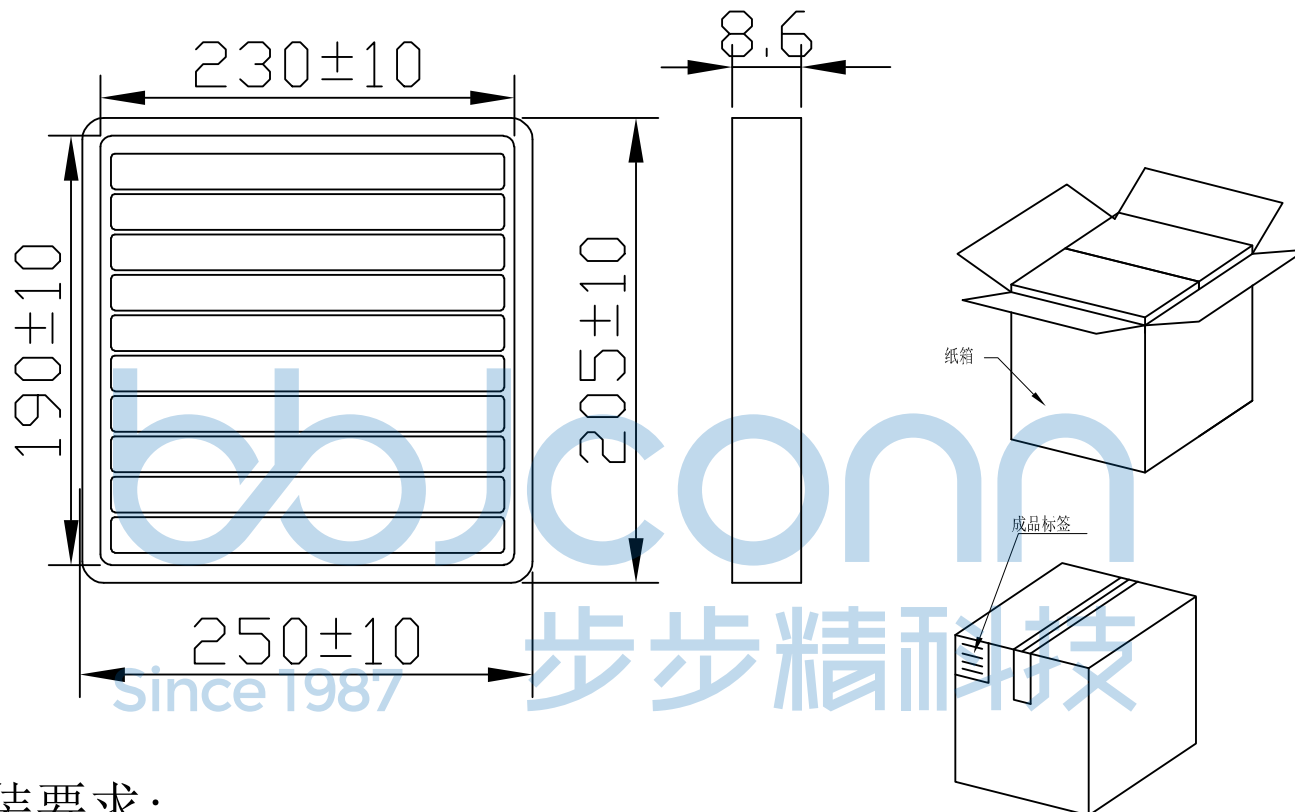
RECOMMENDED P.C.B HOLE LAYOUT
COMPONENT SIDE VIEW (TOLERANCE: +/-0.05)



Pin Number	Signal Name
1	VBUS
2	D-
3	D+
4	GND

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深圳市步步精科技有限公司		NAME: USB 2.0 AF 短体 L=11.05 沉板1.9 端子SMT 平口 LCP黑胶 铁壳 光面 (小米) 盒装	
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X*: ±3° .X*: ±2° .XX*: ±1°	APPD. JM_Zheng	PJ. NO.: UB.01.32-11-1001
CHKD. TSP	DR. LYX	SIZE: A4	DRW NO.:
		FINISH: SEE NOTES	MAT'L.: SEE NOTES
		SCALE: N/A	REV.: A0 UNIT: mm PAGE: 1/2



1. 包装要求:

- 1.1 每盒吸塑盒包装**100**pcs;
- 1.2 每**20**盘放一箱, 共计**2000**PCS;
- 1.3 纸箱外贴上标签。

纸箱规格: 350*210*290

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